

## ABSTRACT

A bump (4, 4A) is formed on each element electrode (5) of a semiconductor device (3), and a thermoplastic resin sheet (7a) is aligned in position with the semiconductor device. The sheet and the semiconductor device are subjected to hot pressing to melt the sheet, forming a thermoplastic resin portion (7) that covers a portion other than the end surface (9) of each bump of the semiconductor device. The thermoplastic resin portion obtained after the hot pressing is cut.

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